

- Independent Asynchronous Inputs and Outputs
- 16 Words by 4 Bits
- Data Rates up to 40 MHz
- Fall-Through Time 14 ns Typical
- 3-State Outputs
- Package Options Include Plastic Small-Outline Package (DW), Plastic Chip Carriers (FN), and Standard Plastic 300-mil DIPs (N)

description

This 64-bit memory features high speed and fast fall-through times. It is organized as 16 words by 4 bits.

A first-in, first-out (FIFO) memory is a storage device that allows data to be written into and read from its array at independent data rates. This FIFO is designed to process data at rates up to 40 MHz in a bit-parallel format, word by word.

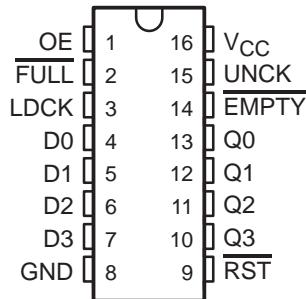
Data is written into memory on a low-to-high transition at the load-clock (LDCK) input and is read out on a low-to-high transition at the unload-clock (UNCK) input. The memory is full when the number of words clocked in exceeds by 16 the number of words clocked out. When the memory is full, LDCK signals have no effect on the data residing in memory. When the memory is empty, UNCK signals have no effect.

Status of the FIFO memory is monitored by the FULL and EMPTY output flags. The FULL output is low when the memory is full and high when it is not full. The EMPTY output is low when the memory is empty and high when it is not empty.

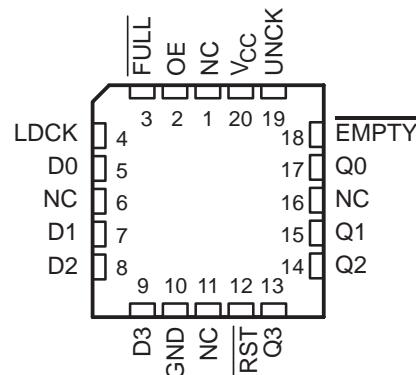
A low level on the reset (RST) input resets the internal stack-control pointers and also sets EMPTY low and sets FULL high. The Q outputs are not reset to any specific logic level. The first low-to-high transition on LDCK, after either a RST pulse or from an empty condition, causes EMPTY to go high and the data to appear on the Q outputs. It is important to note that the first word does not have to be unloaded. Data outputs are noninverting with respect to the data inputs and are at high impedance when the output-enable (OE) input is low. OE does not affect the FULL or EMPTY output flags. Cascading is easily accomplished in the word-width direction but is not possible in the word-depth direction.

The SN74ALS232B is characterized for operation from 0°C to 70°C.

DW OR N PACKAGE
(TOP VIEW)



FN PACKAGE
(TOP VIEW)



NC – No internal connection



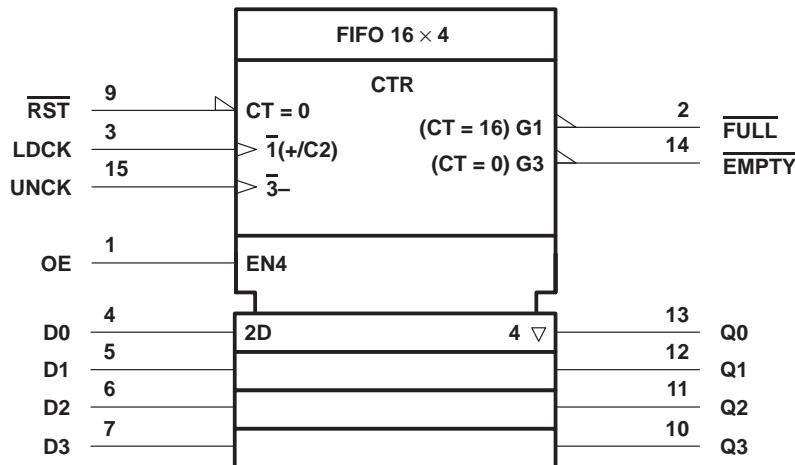
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16 × 4 ASYNCHRONOUS FIRST-IN, FIRST-OUT MEMORY

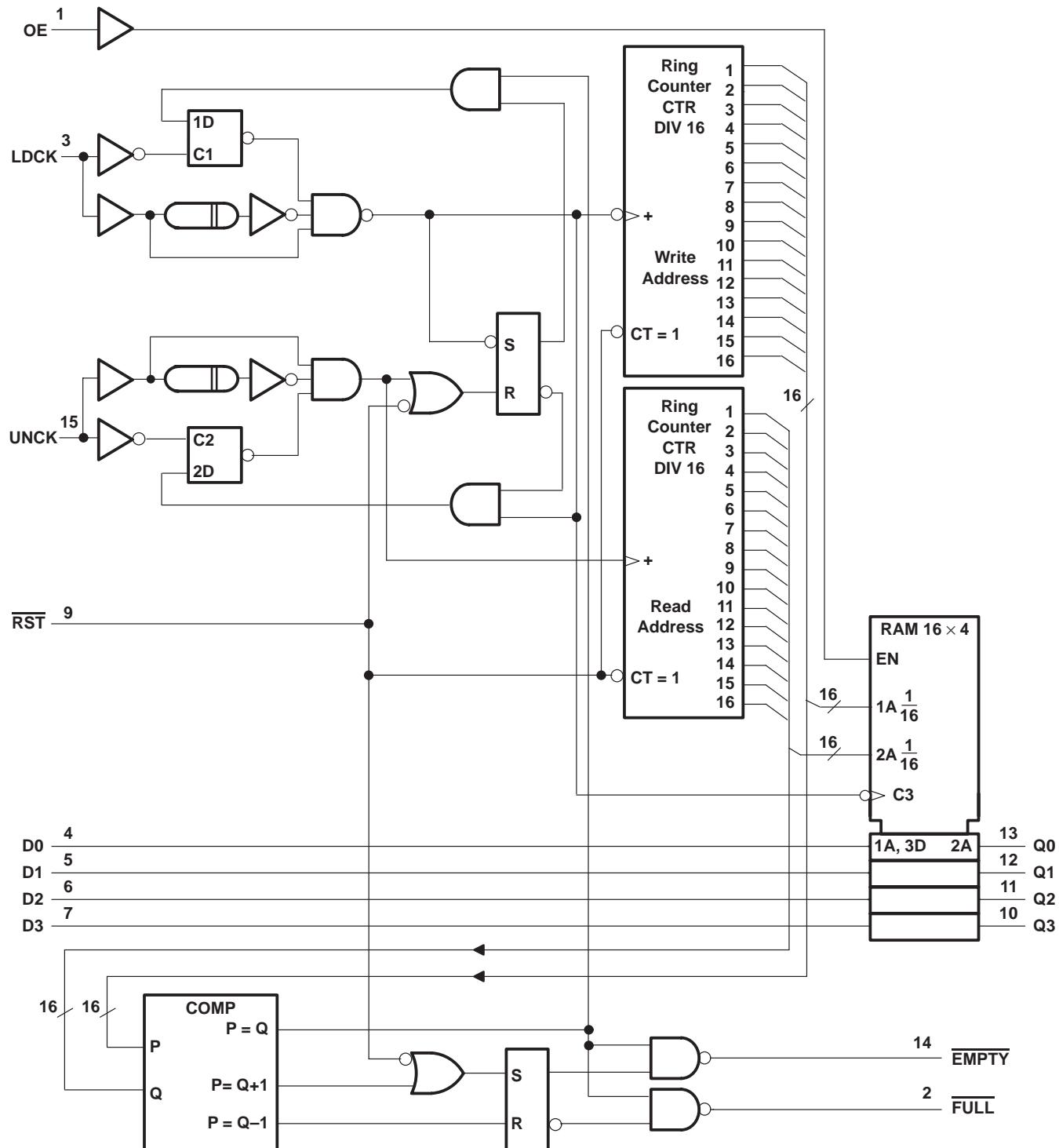
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Standard 91-1984 and IEC Publication 617-12. The symbol is functionally accurate but does not show the details of implementation; for these, see the logic diagram. The symbol represents the memory as if it were controlled by a single counter whose content is the number of words stored at the time. Output data is invalid when the counter content (CT) is 0. Pin numbers shown are for the DW and N packages.

logic diagram (positive logic)



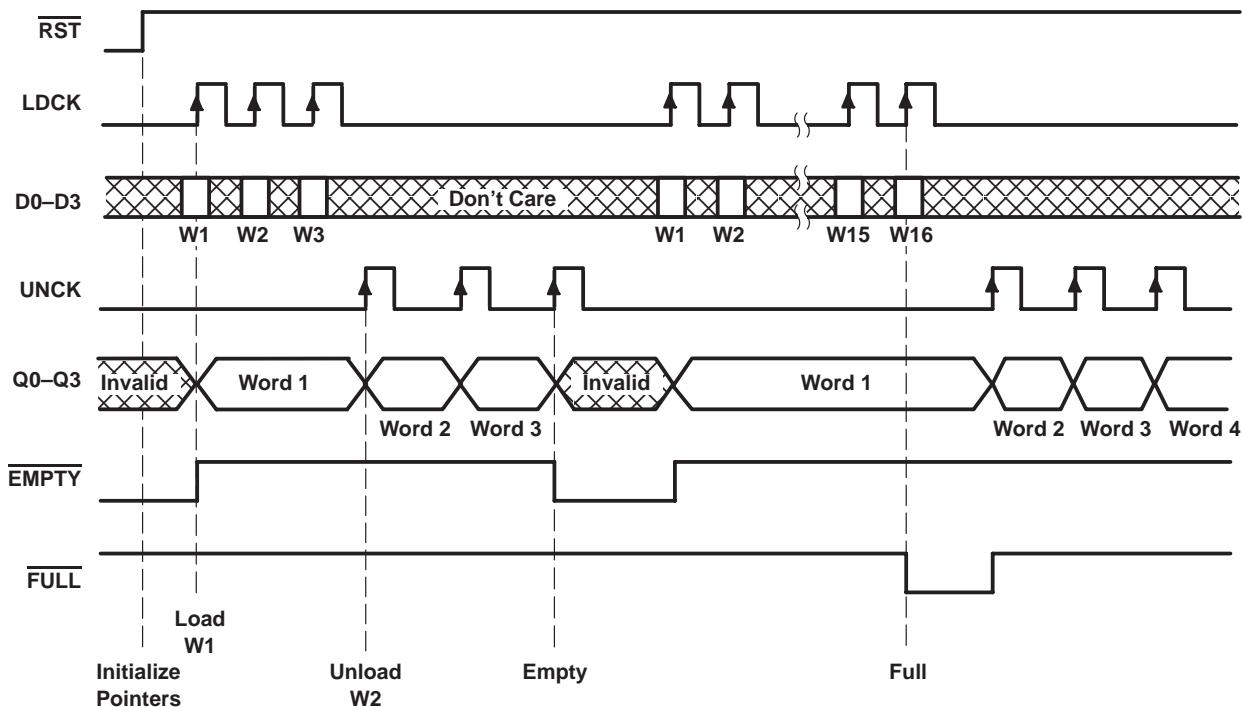
Pin numbers shown are for the DW and N packages.

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timing diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input voltage range, V_I	-0.5 V to 7 V
Voltage range applied to a disabled 3-state output	-0.5 V to 5.5 V
Package thermal impedance, θ_{JA} (see Note 2): DW package	105°C/W
FN package	83°C/W
N package	78°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the "recommended operating conditions" section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to GND.

2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

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recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		4.5	5	5.5	V
V_{IH}	High-level input voltage		2			V
V_{IL}	Low-level input voltage			0.8		V
I_{OH}	High-level output current	Q outputs		-2.6		mA
		FULL, EMPTY		-0.4		
I_{OL}	Low-level output current	Q outputs		24		mA
		FULL, EMPTY		8		
T_A	Operating free-air temperature		0	70		°C

NOTE 3: To ensure proper operation of this high-speed FIFO device, it is necessary to provide a clean signal to the LDCK and UNCK clock inputs. Any excessive noise or glitching on the clock inputs that violates limits for maximum V_{IL} , minimum V_{IH} , or minimum pulse duration can cause a false clock or improper operation of the internal read and write pointers.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT	
V_{IK}	$V_{CC} = 4.5$ V, $I_I = -18$ mA				-1.2	V	
V_{OH}	Q outputs	$V_{CC} = 4.5$ V,	$I_{OH} = -2.6$ mA	2.4	3.2	V	
	FULL, EMPTY	$V_{CC} = 4.5$ V to 5.5 V,	$I_{OH} = -0.4$ mA	$V_{CC}-2$			
V_{OL}	Q outputs	$V_{CC} = 4.5$ V	$I_{OL} = 12$ mA	0.25	0.4	V	
			$I_{OL} = 24$ mA	0.35	0.5		
	FULL, EMPTY	$V_{CC} = 4.5$ V	$I_{OL} = 4$ mA	0.25	0.4		
			$I_{OL} = 8$ mA	0.35	0.5		
I_{OZH}	$V_{CC} = 5.5$ V, $V_O = 2.7$ V			20		µA	
I_{OZL}	$V_{CC} = 5.5$ V, $V_O = 0.4$ V				-20	µA	
I_I	$V_{CC} = 5.5$ V, $V_I = 7$ V			0.1		mA	
I_{IH}	$V_{CC} = 5.5$ V, $V_I = 2.7$ V			20		µA	
I_{IL}	$V_{CC} = 5.5$ V, $V_I = 0.4$ V				-0.2	mA	
I_O^{\ddagger}	$V_{CC} = 5.5$ V, $V_O = 2.25$ V		-30		-112	mA	
I_{CC}	$V_{CC} = 5.5$ V		80	125		mA	

[†] All typical values are at $V_{CC} = 5$ V, $T_A = 25^{\circ}\text{C}$.

[‡] The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, I_{OS} .

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timing requirements over recommended operating free-air temperature range (see Figure 1)

			MIN	NOM	MAX	UNIT
f_{clock}^{\dagger}	Clock frequency	LDCK			40	MHz
		UNCK			40	
t_w	Pulse duration	RST low	18			ns
		LDCK low	15			
		LDCK high	10			
		UNCK low	15			
		UNCK high	10			
t_{su}	Setup time	Data before LDCK \uparrow	8			ns
		LDCK inactive before RST \uparrow	5			
t_h	Hold time	Data after LDCK \uparrow	5			ns
		LDCK inactive after RST \uparrow	5			

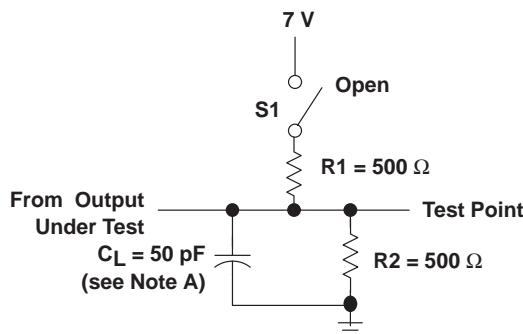
\dagger The maximum possible clock frequency is 40 MHz. The maximum clock frequency when using a 50% duty cycle is 33.3 MHz.

switching characteristics (see Figure 1)

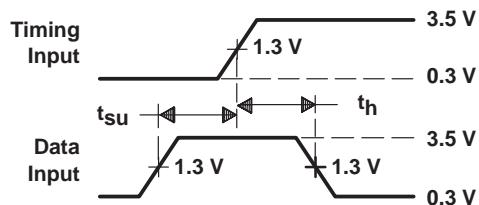
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	TYP \ddagger	MAX	MIN	MAX	UNIT
f_{max}	LDCK, UNCK			50		40		MHz
t_{pd}	LDCK \uparrow	Any Q		14	23	6	30	ns
	UNCK \uparrow			15	23	6	30	
t_{PLH}	LDCK \uparrow	EMPTY	13	20		5	25	ns
t_{PHL}	UNCK \uparrow	EMPTY		15	22	6	27	ns
	RST \downarrow			15	21	5	26	
	LDCK \uparrow		15	22		6	27	
t_{PLH}	UNCK \uparrow	FULL	13	20		5	25	ns
	RST \downarrow		16	23		7	28	
t_{en}	OE \uparrow	Q	5	12		1	14	ns
t_{dis}	OE \downarrow	Q	5	12		1	16	ns

\ddagger Typical values at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

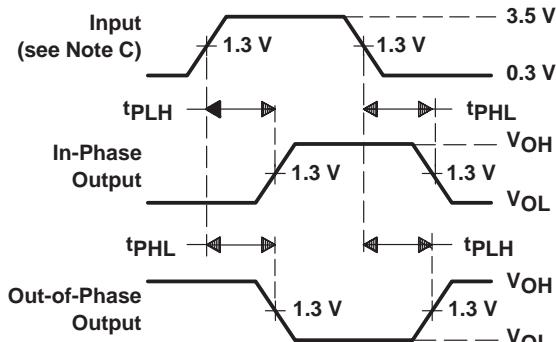
PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT FOR 3-STATE OUTPUTS



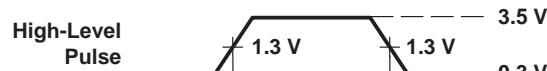
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



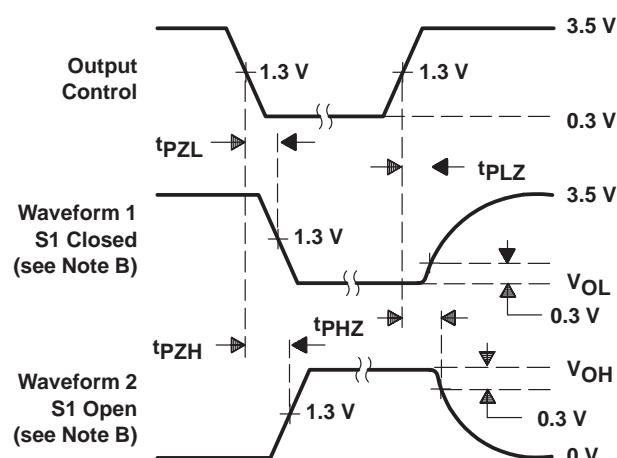
VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

SWITCH POSITION TABLE

PARAMETER	S1
t_{en}	t_{PZH} Open
	t_{PZL} Closed
t_{dis}	t_{PHZ} Open
	t_{PLZ} Closed
t_{pd}	t_{PLH} Open
	t_{PHL} Open



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_0 = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74ALS232BN	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74ALS232BN
SN74ALS232BN.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74ALS232BN

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

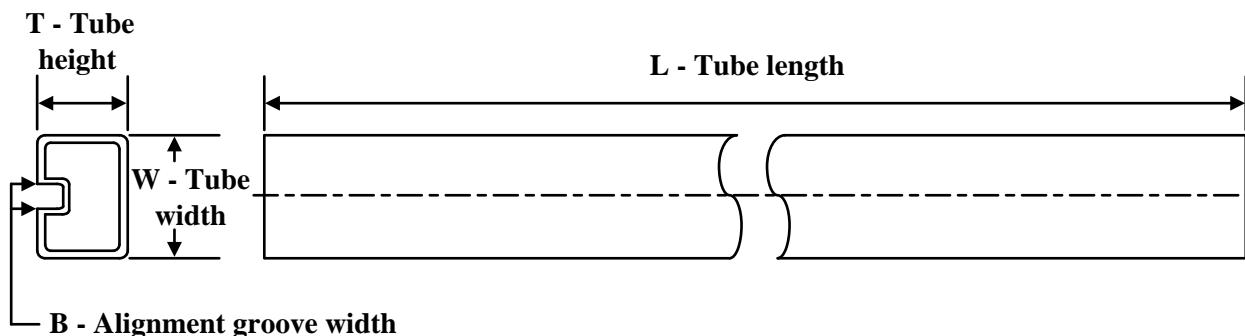
⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74ALS232BN	N	PDIP	16	25	506	13.97	11230	4.32
SN74ALS232BN.A	N	PDIP	16	25	506	13.97	11230	4.32

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



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